

# BLP25M710

Broadband LDMOS driver transistor

Rev. 1 — 29 August 2013

Product data sheet

## 1. Product profile

### 1.1 General description

A 10 W LDMOS power transistor for broadcast and industrial applications in the HF to 2500 MHz band.

Table 1. Application information

Test signal	f (MHz)	I <sub>DQ</sub> (mA)	V <sub>DS</sub> (V)	P <sub>L</sub> (W)	G <sub>p</sub> (dB)	η <sub>D</sub> (%)	IMD <sub>shldr</sub> (dBc)	PAR (dB)
DVB-T	858	110	28	1	20.9	17.1	-47.5 [1]	9.5 [2]
Pulsed RF [3]	2450	80	28	10	16.2	64.5	-	-

[1] Measured [dBc] with delta marker at 4.3 MHz from center frequency.

[2] PAR (of output signal) at 0.01 % probability on CCDF; PAR of input signal = 9.5 dB at 0.01 % probability on CCDF.

[3] Measured at  $\delta = 10\%$ ,  $t_p = 12\ \mu\text{s}$ .

### 1.2 Features and benefits

- Easy power control
- Integrated ESD protection
- Excellent ruggedness
- High efficiency
- Excellent thermal stability
- Designed for broadband operation (HF to 2500 MHz)
- Compliant to Directive 2002/95/EC, regarding Restriction of Hazardous Substances (RoHS)

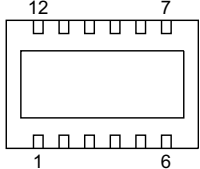
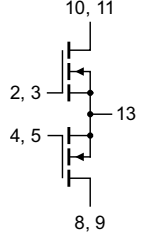
### 1.3 Applications

- Industrial, scientific and medical applications
- Broadcast transmitter applications



## 2. Pinning information

**Table 2. Pinning**

Pin	Description	Simplified outline	Graphic symbol
1, 6, 7, 12	n.c.	 <p>Transparent top view</p>	 <p>aaa-008925</p>
2, 3	gate1		
4, 5	gate2		
8, 9	drain2		
10, 11	drain1		
13	source		

[1] Connected to flange.

## 3. Ordering information

**Table 3. Ordering information**

Type number	Package		
	Name	Description	Version
BLP25M710	HVSON12	plastic thermal enhanced very thin small outline package; no leads; 12 terminals; body 6 × 4 × 0.85 mm	SOT1179-2

## 4. Limiting values

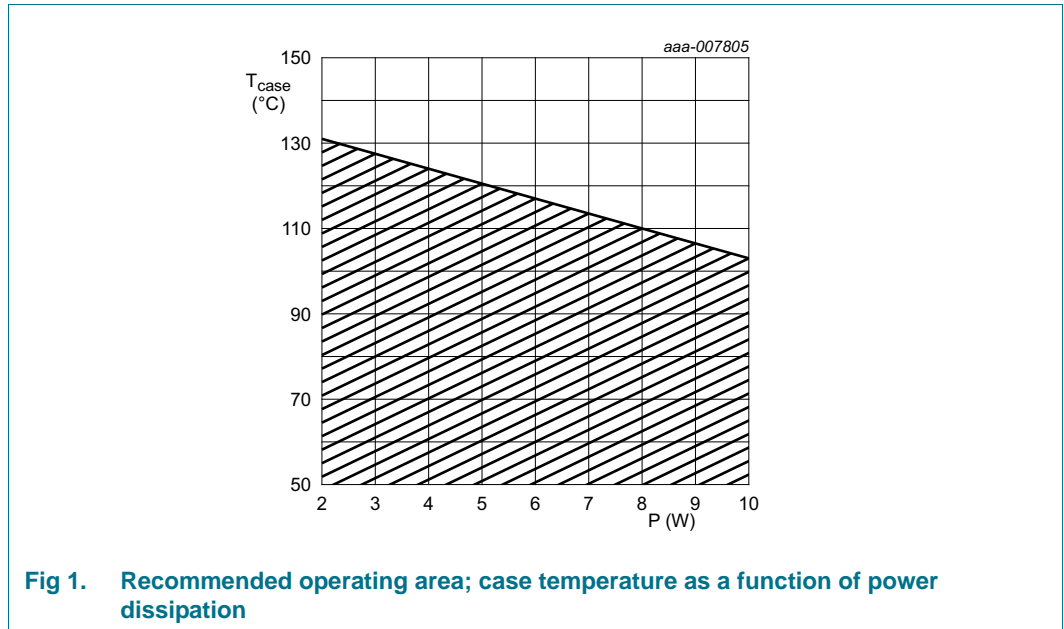
**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DS}$	drain-source voltage		-	65	V
$V_{GS}$	gate-source voltage		-0.5	+13	V
$T_{stg}$	storage temperature		-65	+150	°C
$T_j$	junction temperature		-	150	°C

## 5. Recommended operating conditions

See application note AN11198 for more details.



## 6. Thermal characteristics

**Table 5. Thermal characteristics**

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-c)}$	thermal resistance from junction to case	$T_{case} = 70\text{ }^{\circ}\text{C}; P_L = 2\text{ W}$	3.2	K/W

## 7. Characteristics

**Table 6. DC characteristics**

$T_j = 25\text{ }^{\circ}\text{C}$ ; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{(BR)DSS}$	drain-source breakdown voltage	$V_{GS} = 0\text{ V}; I_D = 0.18\text{ mA}$	65	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$V_{DS} = 10\text{ V}; I_D = 18\text{ mA}$	1.5	1.9	2.3	V
$I_{DSS}$	drain leakage current	$V_{GS} = 0\text{ V}; V_{DS} = 28\text{ V}$	-1.4	-	+1.4	$\mu\text{A}$
$I_{DSX}$	drain cut-off current	$V_{GS} = V_{GS(th)} + 3.75\text{ V}$	-	3.2	-	A
$I_{GSS}$	gate leakage current	$V_{GS} = 11\text{ V}; V_{DS} = 0\text{ V}$	-	-	140	nA
$g_{fs}$	forward transconductance	$V_{DS} = 10\text{ V}; I_D = 18\text{ mA}$	-	160	-	mS
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 3.75\text{ V}; V_{DS} = 10\text{ V}; I_D = 630\text{ mA}$	-	1000	-	$\text{m}\Omega$

**Table 7. RF characteristics**

Test signal: 1-tone pulsed;  $t_p = 50 \mu\text{s}$ ;  $\delta = 10 \%$ ;  $f = 2140 \text{ MHz}$ ; RF performance at  $V_{DS} = 28 \text{ V}$ ;  $I_{DQ} = 110 \text{ mA}$ ;  $T_{case} = 25 \text{ }^\circ\text{C}$ ; unless otherwise specified, in a production circuit.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$G_p$	power gain	$P_{L(AV)} = 2 \text{ W}$	15	16	-	dB
$\eta_D$	drain efficiency	$P_{L(AV)} = 2 \text{ W}$	20	23	-	%
$P_{L(1dB)}$	output power at 1 dB gain compression		11	-	-	W
$RL_{in}$	input return loss	$P_{L(AV)} = 2 \text{ W}$	-	-16	-12	dB

## 8. Test information

### 8.1 Ruggedness in class-AB operation

The BLP25M710 is capable of withstanding a load mismatch corresponding to  $VSWR = 10 : 1$  through all phases under the following conditions:  $V_{DS} = 28 \text{ V}$ ;  $I_{DQ} = 110 \text{ mA}$ ;  $P_L = 10 \text{ W (CW)}$ .

9. Package outline

HVSON12: plastic thermal enhanced very thin small outline package; no leads;  
12 terminals; body 4 x 6 x 0.85 mm

SOT1179-2

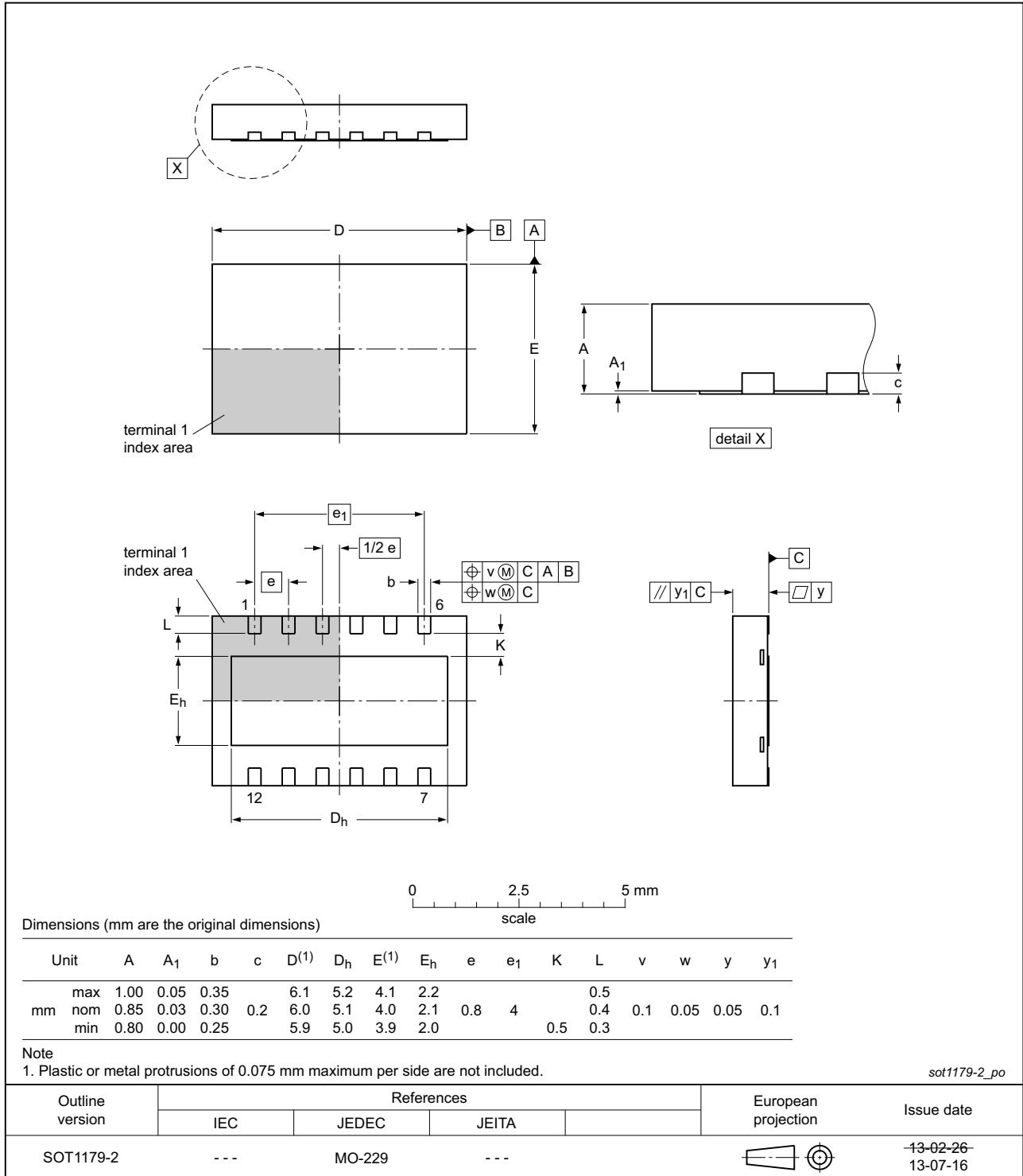


Fig 2. Package outline SOT1179-2 (HVSON12)

## 10. Handling information

### CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the *ANSI/ESD S20.20*, *IEC/ST 61340-5*, *JESD625-A* or equivalent standards.

## 11. Abbreviations

**Table 8. Abbreviations**

Acronym	Description
CCDF	Complementary Cumulative Distribution Function
CW	Continuous Wave
DVB-T	Digital Video Broadcast - Terrestrial
ESD	ElectroStatic Discharge
HF	High Frequency
LDMOS	Laterally Diffused Metal-Oxide Semiconductor
PAR	Peak-to-Average Ratio
VSWR	Voltage Standing-Wave Ratio

## 12. Revision history

**Table 9. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
BLP25M710 v.1	20130829	Product data sheet	-	-

## 13. Legal information

### 13.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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